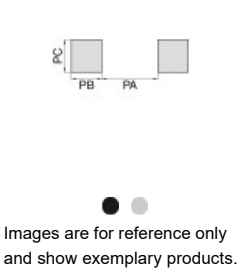


Multilayer Ceramic Chip Capacitors

CGA4J1X8L1E475K125AC

New Product

TDK item description	CGA4J1X8L1E475KT****
Applications	Automotive Grade
Feature	150°C High Temperature Application AEC-Q200 AEC-Q200
Series	CGA4(2012) [EIA 0805]
Status	Production



Size	
Length(L)	2.00mm +0.25,-0.15mm
Width(W)	1.25mm +0.25,-0.15mm
Thickness(T)	1.25mm +0.25,-0.15mm
Terminal Width(B)	0.20mm Min.
Terminal Spacing(G)	0.50mm Min.
Recommended Land Pattern (PA)	1.00mm to 1.30mm(Flow Soldering) 0.90mm to 1.20mm(Reflow Soldering)
Recommended Land Pattern (PB)	1.00mm to 1.20mm(Flow Soldering) 0.70mm to 0.90mm(Reflow Soldering)
Recommended Land Pattern (PC)	0.80mm to 1.10mm(Flow Soldering) 0.90mm to 1.20mm(Reflow Soldering)

Electrical Characteristics	
Capacitance	4.7μF ±10%
Rated Voltage	25VDC
Temperature Characteristic	X8L(+15,-40%)
Dissipation Factor (Max.)	5%
Insulation Resistance (Min.)	106MΩ

Other	
Soldering Method	Wave (Flow) Reflow
AEC-Q200	Yes
Packing	Blister (Plastic)Taping [180mm Reel]
Package Quantity	2000pcs

Characteristic Graph (This is reference data, and does not guarantee the products characteristics.)



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RoHS

REACH SVHC-Free

Halogen Free

Lead Free

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Characterization Sheet	

CGA4J1X8L1E475K125AC

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Change settings

Capacitance

CGA4J1X8L1E475K125AC

Change settings

DC Bias Characteristic

CGA4J1X8L1E475K125AC

Change settings

Temperature Characteristic

CGA4J1X8L1E475K125AC(No Bias)CGA4J1X8L1E475K125AC(DC Bias = 12.5)

Change settings

Ripple Temperature Rising

CGA4J1X8L1E475K125AC(100 kHz)CGA4J1X8L1E475K125AC(500 kHz)CGA4J1X8L1E475K125AC(1 MHz)

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